1   Package summary

Terminal position code	B (bottom)
Package type descriptive code	VSON6
Package style descriptive code	VSON (very thin small outline; no leads)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	26-08-2020
Manufacturer package code	98ASA01688D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	1.3	1.4	1.5	mm
package width	1.3	1.4	1.5	mm
package height	0.8	0.85	0.9	mm
nominal pitch	-	0.5	-	mm
actual quantity of termination	-	6	-	

2 Package outline

PDFN-COL-6 I/O
1.4 X 1.4 X 0.85 PKG, 0.5 PITCH

SOT2078-1

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DATE: 26 AUG 2020

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON JEDEC	DRAWING NUMBER: 98ASA01688D	REVISION: 0	PAGE:
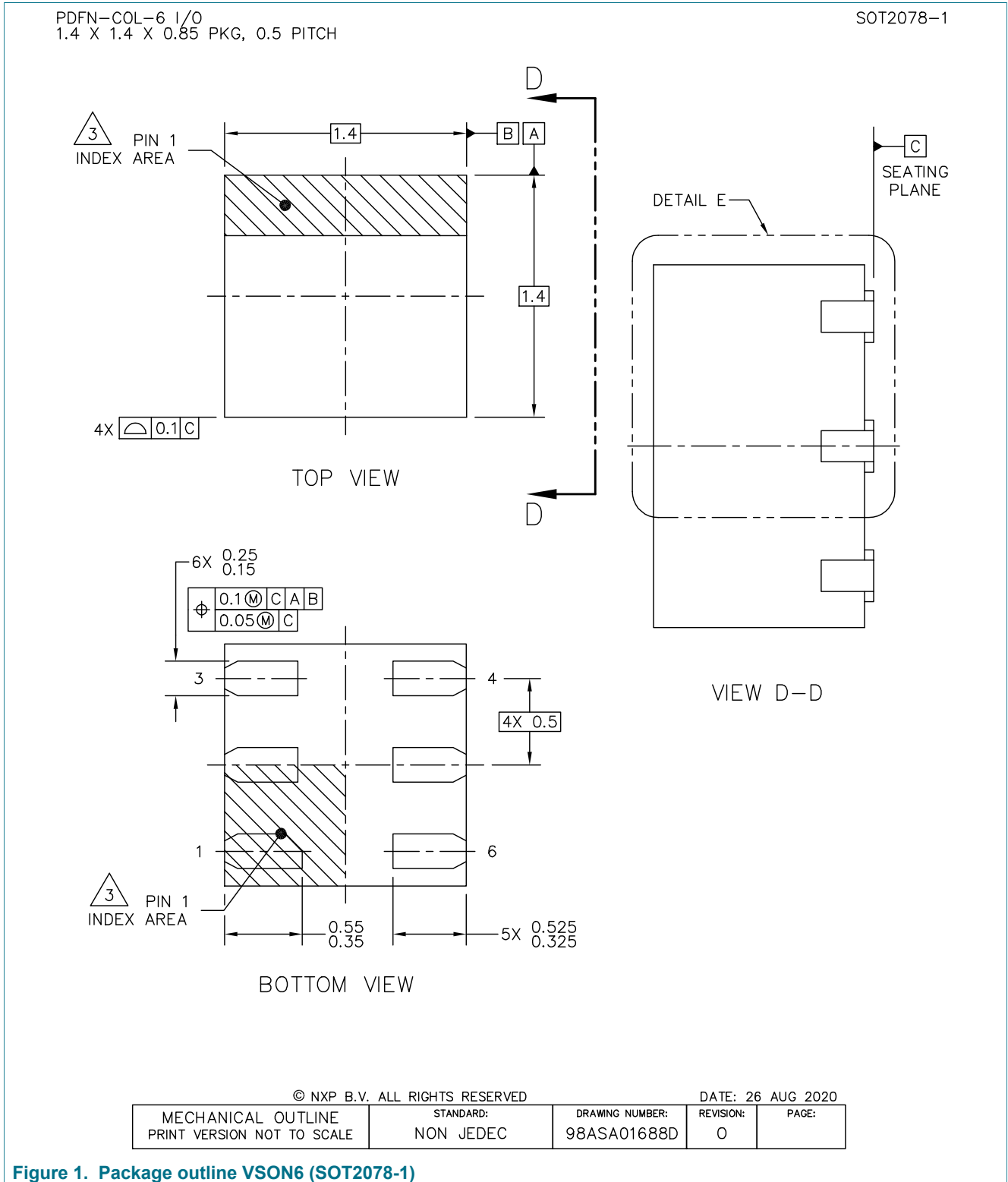
Figure 1. Package outline VSON6 (SOT2078-1)

SOT2078-1

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Package information

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PDFN-COL-6 I/O
1.4 X 1.4 X 0.85 PKG, 0.5 PITCH
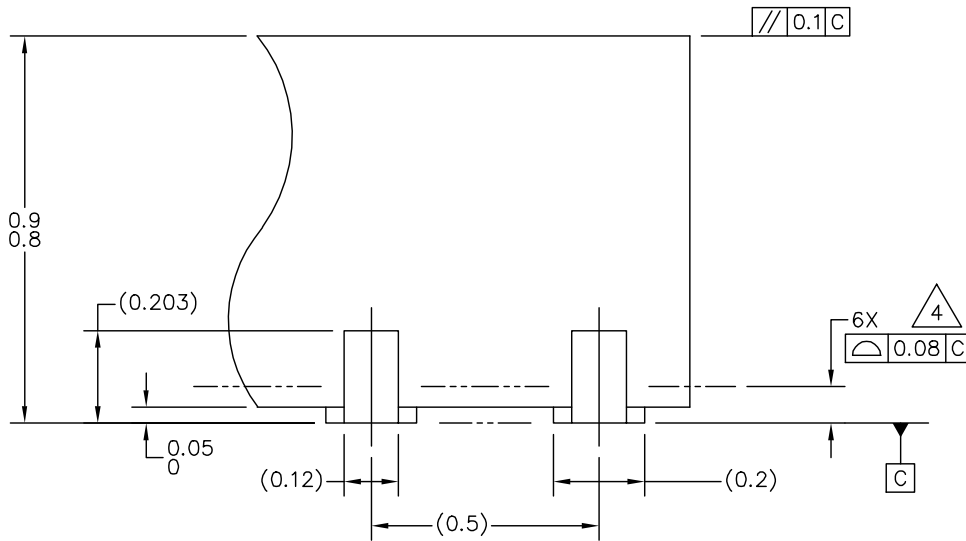
SOT2078-1

DETAIL E
VIEW ROTATED 90°CW

DATE: 26 AUG 2020

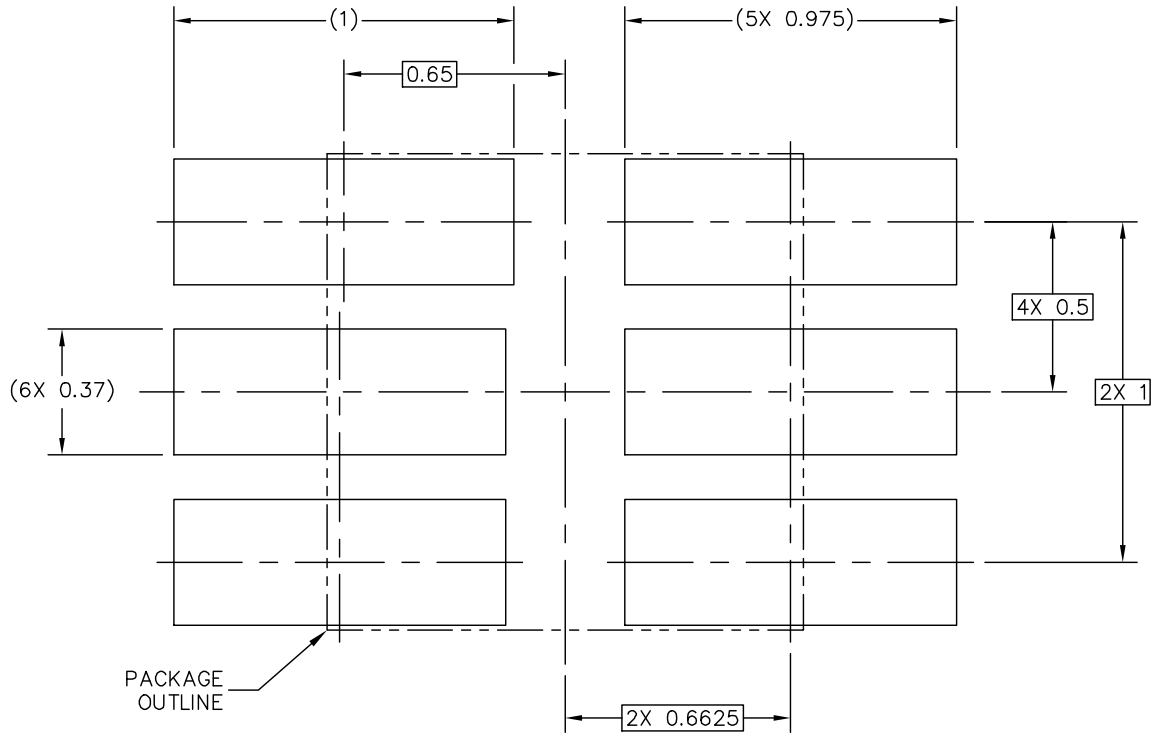| MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON JEDEC	DRAWING NUMBER: 98ASA01688D	REVISION: O	PAGE:

Figure 2. Package outline detail of VSON6 (SOT2078-1)

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Package information

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3   Soldering

PDFN-COL-6 I/O
1.4 X 1.4 X 0.85 PKG, 0.5 PITCH

SOT2078-1

(1)   (5X 0.975)

0.65

(6X 0.37)

4X 0.5

2X 1

PACKAGE
OUTLINE

2X 0.6625

PCB DESIGN GUIDELINES – SOLDER MASK OPENING PATTERN

THIS SHEET SERVES ONLY AS A GUIDELINE TO HELP DEVELOP A USER SPECIFIC SOLUTION.
DEVELOPMENT EFFORT WILL STILL BE REQUIRED BY END USERS TO OPTIMIZE PCB MOUNTING
PROCESSES AND BOARD DESIGN IN ORDER TO MEET INDIVIDUAL/SPECIFIC REQUIREMENTS.
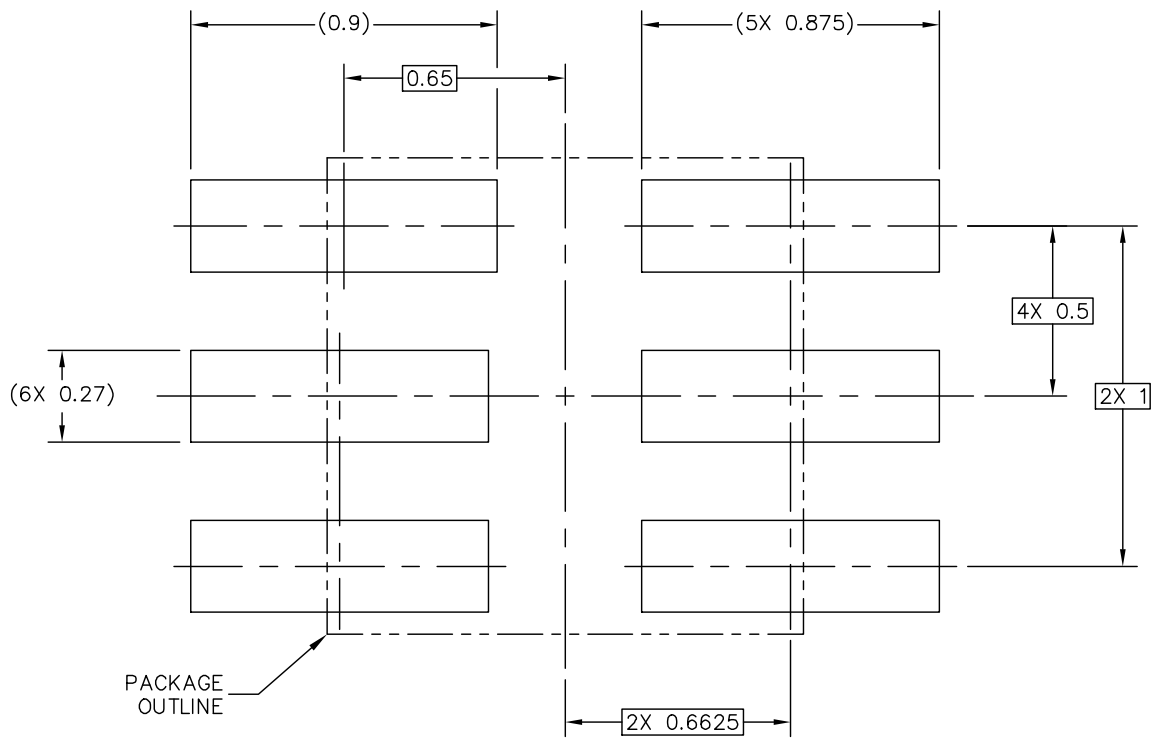
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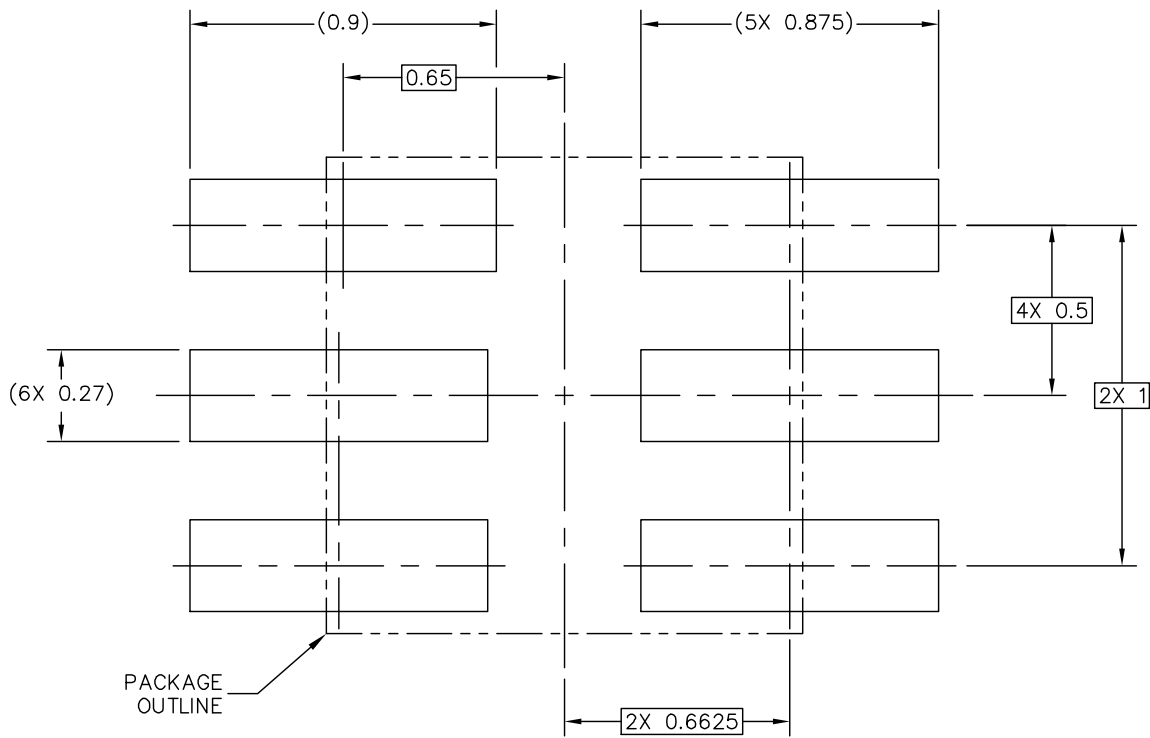| MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON JEDEC	DRAWING NUMBER: 98ASA01688D	REVISION: O	PAGE:

Figure 3. Reflow soldering footprint part1 for VSON6 (SOT2078-1)

Package information

7 September 2020

PDFN-COL-6 I/O
1.4 X 1.4 X 0.85 PKG, 0.5 PITCH

SOT2078-1

(0.9)

0.65

(5X 0.875)

4X 0.5

2X 1

(6X 0.27)

PACKAGE
OUTLINE

2X 0.6625

PCB DESIGN GUIDELINES — I/O PADS AND SOLDERABLE AREA

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DATE: 26 AUG 2020

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON JEDEC	DRAWING NUMBER: 98ASA01688D	REVISION: O	PAGE:

Figure 4. Reflow soldering footprint part2 for VSON6 (SOT2078-1)

SOT2078-1

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Package information

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PDFN-COL-6 I/O
1.4 X 1.4 X 0.85 PKG, 0.5 PITCH

SOT2078-1

(0.9)

0.65

(5X 0.875)

(6X 0.27)

4X 0.5

2X 1

PACKAGE
OUTLINE

2X 0.6625

RECOMMENDED STENCIL THICKNESS 0.1

PCB DESIGN GUIDELINES – SOLDER PASTE STENCIL

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PROCESSES AND BOARD DESIGN IN ORDER TO MEET INDIVIDUAL/SPECIFIC REQUIREMENTS.

DATE: 26 AUG 2020

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON JEDEC	DRAWING NUMBER: 98ASA01688D	REVISION: O	PAGE:

Figure 5. Reflow soldering footprint part3 for VSON6 (SOT2078-1)

SOT2078-1

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Package information

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PDFN-COL-6 I/O
1.4 X 1.4 X 0.85 PKG, 0.5 PITCH

SOT2078-1

NOTES:

1. ALL DIMENSIONS ARE IN MILLIMETERS.

2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.

3. PIN 1 FEATURE SHAPE, SIZE AND LOCATION MAY VARY.

4. COPLANARITY APPLIES TO LEADS.

5. MIN. METAL GAP SHOULD BE 0.15 MM.

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Figure 6. Package outline note VSON6 (SOT2078-1)

4 Legal information

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